

### CONFERENCES IN 2008:

IEEE Workshop on **Signal Propagation on Interconnects** (SPI 2008) [www.univ-brest.fr/SPI](http://www.univ-brest.fr/SPI)  
May 12-15, 2008 Avignon, France  
Contact: Denis Deschacht, Denis.Deschacht@lirmm.fr

58th **Electronic Components and Technology Conference** (ECTC 2008) [www.ectc.net](http://www.ectc.net)  
May 27 - 30, 2008; Disney's Contemporary Resort  
Lake Buena Vista, Florida USA  
Contact: Jean Trehwella, IBM, jeanmh@us.ibm.com

Intersociety Conference on **Thermal and Thermomechanical Phenomena in Electronic Systems** (I-THERM 2008) [www.ithermconference.org](http://www.ithermconference.org)  
May 28-31, 2008 Orlando, FL USA  
Contact: Ms. Kelly Sutton, epd@enr.arizona.edu

18th IEEE **Semiconductor Wafer Test Workshop** (SWTW 2008) [www.swtest.org](http://www.swtest.org)  
June 8-11, 2008 San Diego, CA USA  
Contact: Bill Mann, william.mann@ieee.org

International **Conference on Electronics Packaging** (ICEP 2008) [www.jiep.or.jp/icep](http://www.jiep.or.jp/icep)  
June 10-12, 2008 Tokyo Big Sight, Tokyo, Japan  
Contact: ICEP Secretariat at icep@jiep.or.jp

Joint Int'l Conference on **Electronic Packaging Technology & High Density Packaging** (ICEPT-HDP) [www.icept.org](http://www.icept.org)  
July 28-31, 2008 Shanghai, China  
CFP Abstracts Deadline: April 11, 2008  
Contact: ICEPT-HDP Secretariat at icept2008@fudan.edu.cn

Joint Event: 7th Int'l IEEE Conference on **Polymers and Adhesives in Microelectronics and Photonics** (POLYTRONIC 2008) with **PORTABLE 2008**  
August 17-22, 2008 Edelweiss Hotel & Conference Center  
[www.polytronic2008.com](http://www.polytronic2008.com)  
Garmisch-Partenkirchen, Germany  
Contact: info@polytronic2008.com

**Electronics System-Integration Technology Conference** (ESTC 2008) [www.estc.biz](http://www.estc.biz)  
September 1-4, 2008; University of Greenwich  
Greenwich, London UK  
Contact: Chris Bailey, Greenwich University,  
chris.bailey@estc.biz

2008 Workshop on **Accelerated Stress Testing & Reliability** (ASTR) [www.ewh.ieee.org/soc/cpmt/tc7/ast2008](http://www.ewh.ieee.org/soc/cpmt/tc7/ast2008)  
October 1 - 3, 2008 Portland, OR USA  
Abstracts Due: April 28, 2008  
Contact: Cheryl Tulkoff, National Instruments,  
cheryl.tulkoff@ni.com

Joint Event: 3rd **Int'l Microsystems, Packaging, Assembly and Circuits Technology** (IMPACT) Conference, with the 10th Int'l Conference on **Electronics Materials and Packaging** (EMAP) [www.impact-emap.org](http://www.impact-emap.org)  
October 22 - 24, 2008 Taipei, Taiwan  
Abstracts Due: May 31, 2008  
Contact: Mr. Long-Shien Lin, tw2008@isu.edu.tw

54th IEEE **Holm Conference on Electrical Contacts** (HOLM 2008) [www.ewh.ieee.org/soc/cpmt/tc1/h2008/h2008top.html](http://www.ewh.ieee.org/soc/cpmt/tc1/h2008/h2008top.html)  
27-29 October, 2008 Orlando, FL USA  
Contact: Chi H. Leung, AMID DODUCO,  
cleung@amidoduco.com

33rd Int'l **Electronics Manufacturing Technology Symposium** (IEMT 2008) [www.cpmt.ieemalaysia.org](http://www.cpmt.ieemalaysia.org)  
November 4-6, 2008; Penang, Malaysia  
Contact: Ir. Dr. Cheong Kuan Yew, USM  
cheong@eng.usm.my

9th **VLSI Packaging Workshop in Japan**  
December 1 - 2, 2008; Kyoto, Japan [vlsi-pkg-ws.org](http://vlsi-pkg-ws.org)  
Abstracts Due: May 31, 2008  
Contact: Michitaka Kimura, Renesas Technology Corp,  
kimura.michitaka@renesas.com

10th **Electronics Packaging Technology Conference** (EPTC 2008) [www.eptc-ieee.net](http://www.eptc-ieee.net)  
December 9-12, 2008; Singapore  
Abstracts due June 10, 2008  
Contact: Dr. Tong Yan Tee, tytee@amkor.com

**Electrical Design of Advanced Packaging and Systems** (EDAPS 2008) [www.edaps2008.org](http://www.edaps2008.org)  
December 10-12, 2008 COEX Conference Center  
Seoul, Korea  
Papers due: July 31, 2008  
Contact: S.M Yang, yangsm@ee.kaist.ac.kr (Office: 82-42-869-5458)

2nd Int'l Conference on **Thermal issues in Emerging Technologies, Theory and Applications** (ThETA2)  
December 17-20, 2008 Cairo, Egypt [www.thetaconf.org](http://www.thetaconf.org)  
Papers due: July 31, 2008  
Contact: thetaconf@gmail.com

### CONFERENCES IN 2009:

**European Microelectronics and Packaging Conference & Exhibition** (EMPC 2009) [www.empc2009.org](http://www.empc2009.org)  
June 14-17, 2009 Rimini, Italy  
Abstracts due: December 31, 2008  
Contact: Pragma Congressi, segreteria@empc2009.org